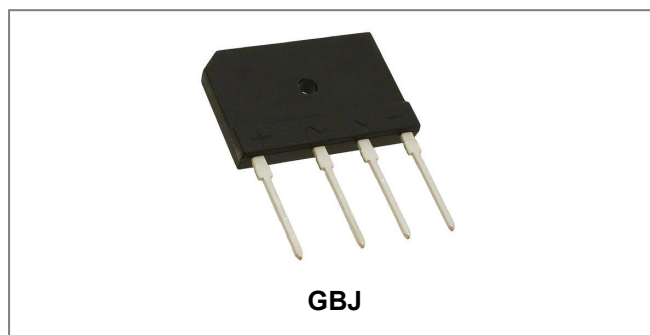


## GBJ35005-GBJ3510

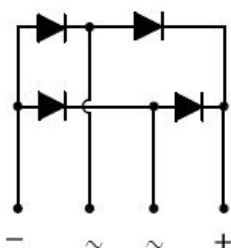
### Single-Phase 35.0A Glass Passivated Bridge Rectifier



#### Features

- Glass passivated die construction
- Low forward voltage drop
- High current capability
- High surge current capability
- Plastic material-UL flammability 94V-0
- This is a Pb – Free Device
- All SMC parts are traceable to the wafer lot
- Additional testing can be offered upon request

#### Circuit Diagram



#### Mechanical Data

- Case: GBJ, Molded plastic
- Terminals: Plated leads solderable per MIL-STD-202, Method 208
- Polarity: as marked on case
- Mounting Position: Any
- Lead Free: For RoHS / Lead Free Version
- Weight: 6.8 grams(approx)

#### Maximum Ratings @ $T_A=25^{\circ}\text{C}$ unless otherwise specified

Type Number	Symbol	GBJ 35005	GBJ 3501	GBJ 3502	GBJ 3504	GBJ 3506	GBJ 3508	GBJ 3510	Units
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	$V_{RRM}$ $V_{RWM}$ $V_{DC}$	50	100	200	400	600	800	1000	V
RMS Reverse Voltage	$V_{RMS}$	35	70	140	280	420	560	700	V
Average forward rectified output current @ $T_A = 100^{\circ}\text{C}$	$I_{(AV)}$	35.0							A
Peak Forward Surge Current, 8.3ms single half-sine-wave superimposed on rated load (JEDEC method)	$I_{FSM}$	320							A

**Electrical Characteristics @ $T_A=25^{\circ}\text{C}$  unless otherwise specified**

Type Number	Symbol	GBJ 35005	GBJ 3501	GBJ 3502	GBJ 3504	GBJ 3506	GBJ 3508	GBJ 3510	Units
Forward Voltage (per element) @ $I_F=17.5\text{A}$ @ $I_F=35\text{A}$	$V_F$				1.0 1.1				V
Peak Reverse Current @ $T_A=25^{\circ}\text{C}$ At Rated DC Blocking Voltage @ $T_A=125^{\circ}\text{C}$	$I_{RM}$				5 500				$\mu\text{A}$
Typical Junction Capacitance(per leg) (Note 1)	$C_J$				140				pF

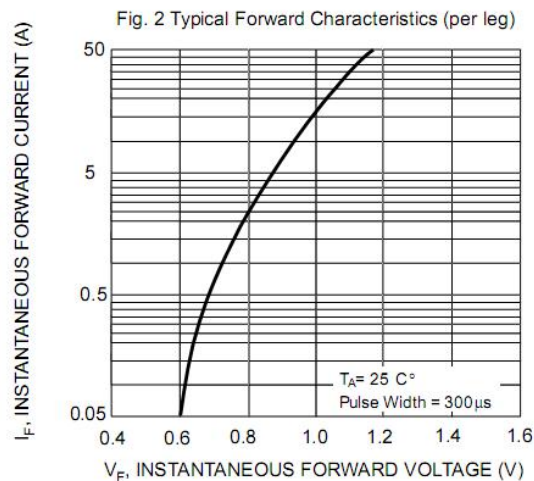
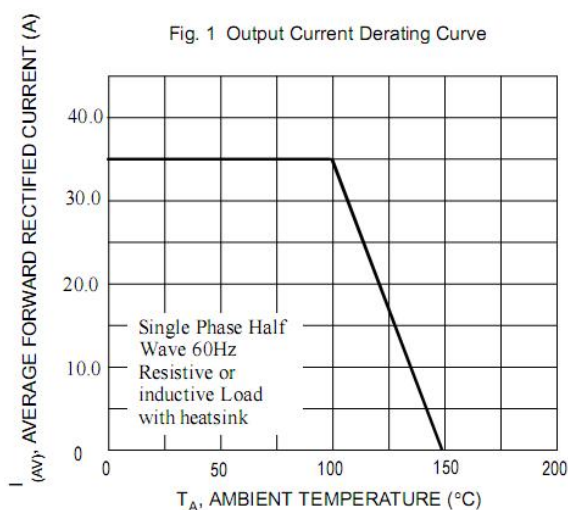
\* Pulse width < 300  $\mu\text{s}$ , duty cycle < 2%

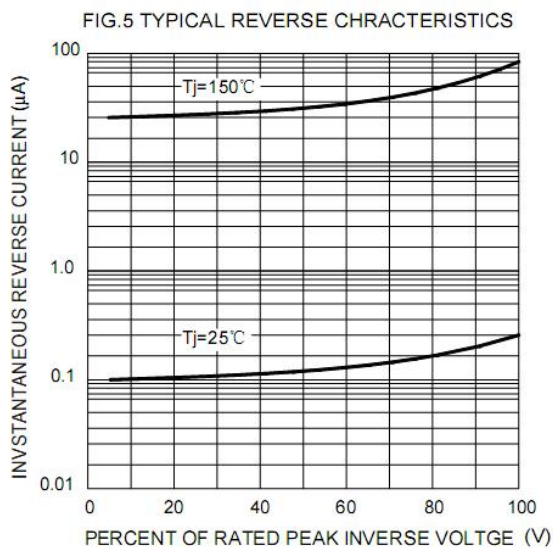
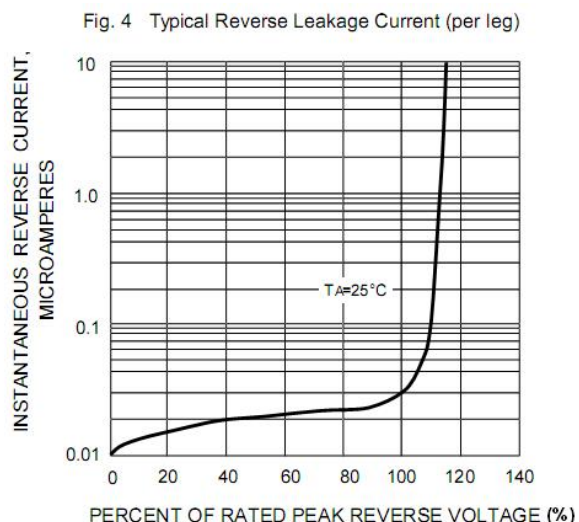
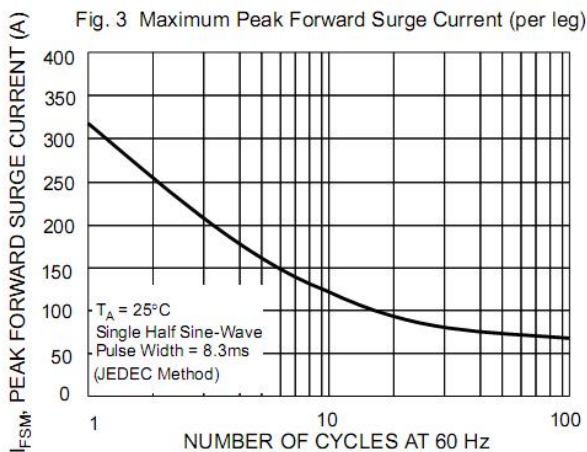
**Thermal-Mechanical Specifications:**

Type Number	Symbol	GBJ 35005	GBJ 3501	GBJ 3502	GBJ 3504	GBJ 3506	GBJ 3508	GBJ 3510	Units
Typical Thermal Resistance Junction to Ambient, Without heatsink Typical Thermal Resistance Junction to Case, With heatsink(Note 2)	$R_{\theta JA}$ $R_{\theta JC}$				22 1.5				$^{\circ}\text{C/W}$
Operating and Storage Temperature Range	$T_J, T_{STG}$				-55 to +150				$^{\circ}\text{C}$

Note: 1- Measured at 1 MHz and applied reverse voltage of 4.0 VDC.  
2-The heatsink are dimensioned as 25\*17\*4cm and the material is aluminum.

**Ratings and Characteristics Curves**

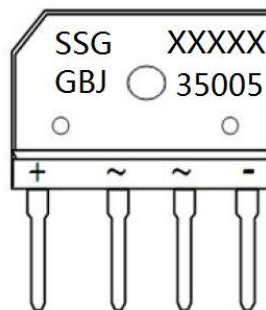




**Ordering Information**

Device	Package	Plating	Shipping
GBJ35005 THRU GBJ3510	GBJ(Pb-Free)	Pure Sn	15pcs / tube

**Marking Diagram**

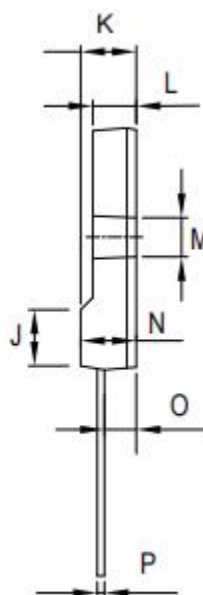
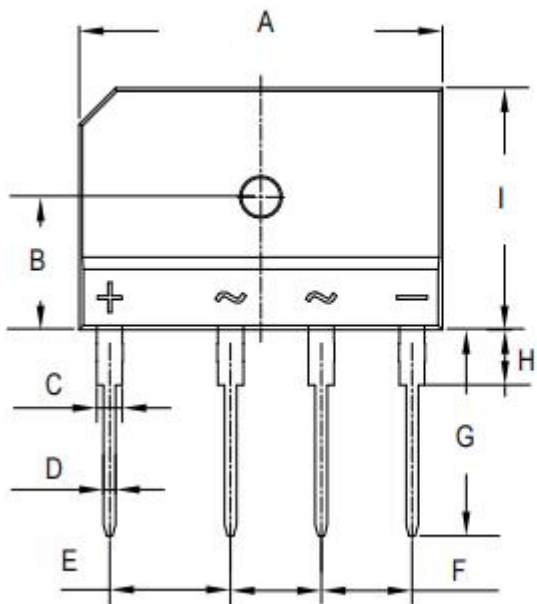


Where XXXXX is YYWWL

SSG = SSG  
YY = Year  
WW = Week  
L = Lot Number  
GBJ35005 = Type Number

**Cautions:** Molding resin  
Epoxy resin UL:94V-0

**Mechanical Dimensions GBJ (Inches/Millimeters)**



Dimensions	Millimeters		Inches	
	Min	Max	Min	Max
A	29.7	30.3	1.169	1.193
B	10.8	11.2	0.425	0.441
C	1.9	2.3	0.075	0.091
D	0.9	1.1	0.035	0.043
E	9.0	11.0	0.354	0.433
F	7.3	7.7	0.287	0.303
G	17.0	18.0	0.699	0.709
H	3.8	4.2	0.150	0.165
I	19.7	20.3	0.776	0.799
J	4.8	5.2	0.189	0.205
K	4.4	4.8	0.173	0.189
L	3.4	3.8	0.134	0.150
M	3.1	3.4	0.122	0.134
N	4.4	4.8	0.173	0.189
O	2.4	2.8	0.094	0.110
P	0.5	0.7	0.020	0.028

**Technical Data  
Data Sheet N1805, Rev. C**



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